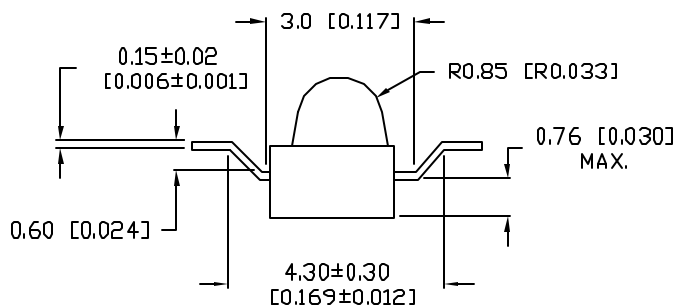
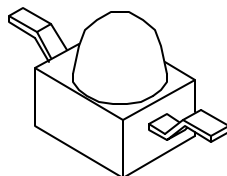
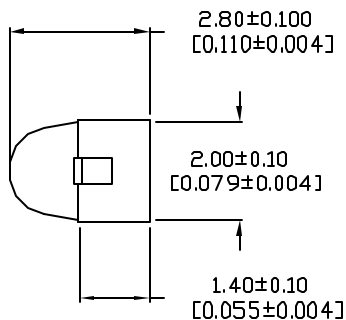
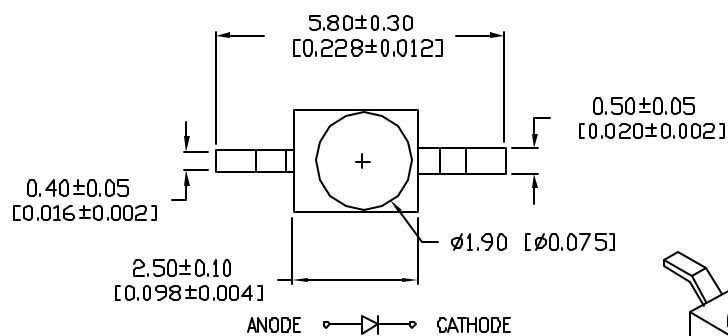


UNCONTROLLED DOCUMENT

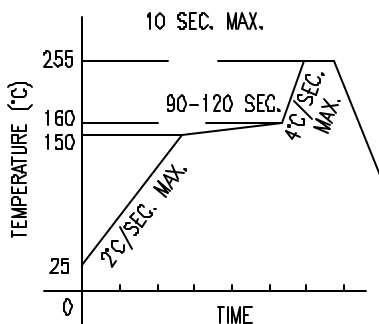
PART NUMBER
SSL-LXA228SIC-TR31

REV.
B

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #11148	11.15.06
B	E.C.N. #11508.	06.13.08

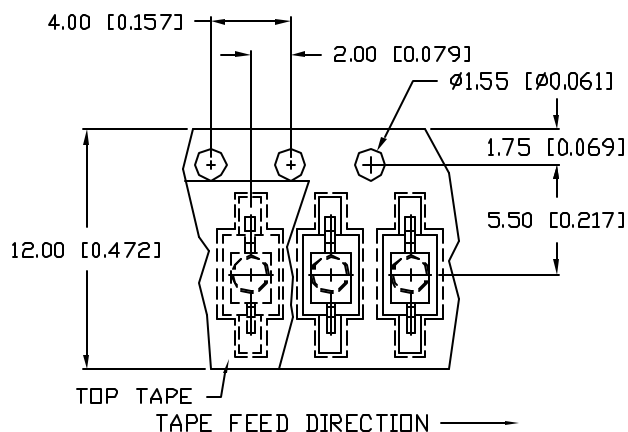
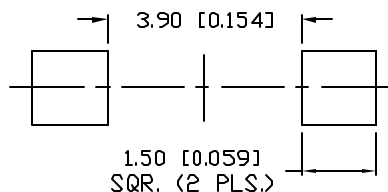


LEAD FREE REFLOW PROFILE



TOTAL TIME ABOVE 220°C IS 60 SECONDS MAX.

RECOMMENDED SOLDER PAD LAYOUT



ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^{\circ}\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		636		nm	
FORWARD VOLTAGE		2.0	2.6	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_f=100\mu\text{A}$
AXIAL INTENSITY		475		mcd	$I_f=20\text{mA}$
VIEWING ANGLE		25		2x theta	
EMITTED COLOR:	RED				
EPOXY LENS FINISH:	WATER CLEAR				

LIMITS OF SAFE OPERATION AT 25°C PER DIE

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	160	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	100	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING, STORAGE TEMP.	-40 TO +85	°C
SOLDERING TEMP.	+260	°C
2.0mm FROM BODY	3 SEC. MAX	

* $t < 10\mu\text{s}$

NOTES:

- 1,000 PIECES PER REEL.
- THE CATHODE IS ORIENTED TOWARDS THE TAPE SPROCKET HOLE.



CAUTION: MOISTURE SENSITIVE DEVICE
PER JEDEC LEVEL 4 STANDARDS



UNCONTROLLED DOCUMENT

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.038), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030), MIN=+DECIMAL PRECISION MAX.=+0.00 -DECIMAL PRECISION

REV. B PART NUMBER SSL-LXA228SIC-TR31

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636nm AlInGaP RED AXIAL LEADED LED,
WATER CLEAR LENS, Z BEND, TAPE AND REEL.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: JC	CHECKED BY:	APPROVED BY:	DATE: 11.15.06
			PAGE: 1 OF 1
			SCALE: N/A